

ECN/PCN No.: 4128

| For Manufacturer | | | |
|--|--|--|--|
| Product Description: PLASTIC SMD MEMS OSCILLATOR | Abracon Part Number / Part Series: EMK33 | <input type="checkbox"/> Documentation only <input type="checkbox"/> ECN <input checked="" type="checkbox"/> EOL | <input checked="" type="checkbox"/> Series <input type="checkbox"/> Part Number |
| Affected Revision: L | New Revision: EOL | Application: | <input type="checkbox"/> Safety <input checked="" type="checkbox"/> Non-Safety |
| Prior to Change: Active https://abracon.com/datasheets/Ecliptek/EMK33.pdf | | | |
| After Change: EOL | | | |
| Cause/Reason for Change: Discontinuation of manufacturing capability. | | | |
| Change Plan | | | |
| Effective Date: 2/7/2022 | Additional Remarks: N/A | | |
| Change Declaration: N/A | | | |
| Issued Date: 2/7/2022 | Issued By: | Issued Department: | |
| Approval: | Approval: | Approval: | |
| For Abracon EOL only | | | |
| Last Time Buy (if applicable): 5/7/2022 | Alternate Part Number / Part Series: ASEDV (3.2x2.5mm) | | |
| Additional Approval: | Additional Approval: | Additional Approval: | |
| Customer Approval (If Applicable) | | | |
| Qualification Status: <input type="checkbox"/> Approved <input type="checkbox"/> Not accepted <i>Note: It is considered approved if there is no feedback from the customer 1 month after ECN/PCN is released.</i> | | | |
| Customer Part Number: | | Customer Project: | |
| Company Name: | Company Representative: | Representative Signature: | |
| Customer Remarks: | | | |

REGULATORY COMPLIANCE

| | | | | |
|--|--|--|--|---|
|  <p>Lead Free COMPLIANT</p> |  <p>EU RoHS 2011/65 + 2015/863 COMPLIANT</p> |  <p>China RoHS COMPLIANT</p> |  <p>REACH SVHC COMPLIANT</p> |  <p>DRC CONFLICT FREE</p> |
|--|--|--|--|---|

ITEM DESCRIPTION

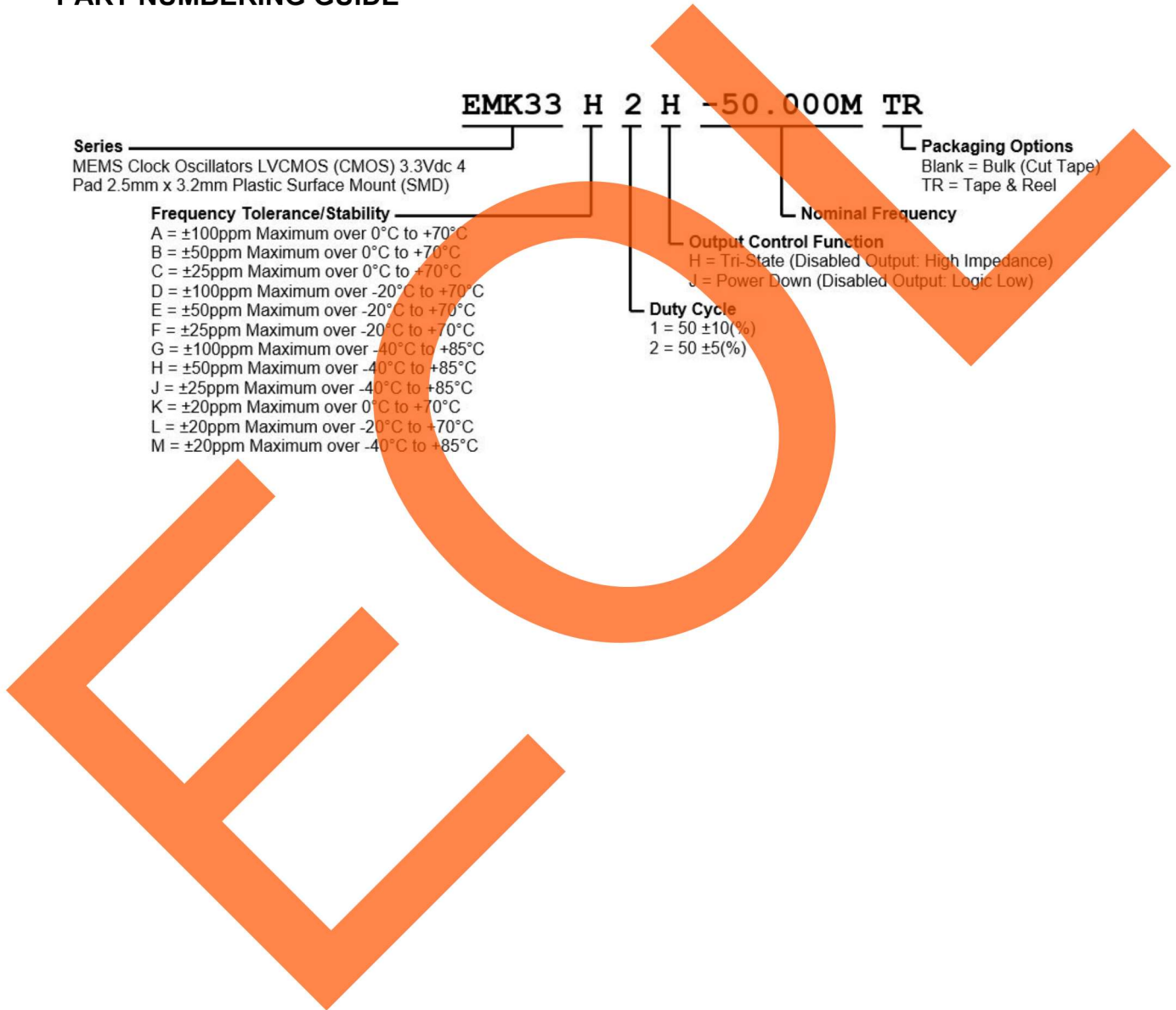
MEMS Clock Oscillators LVCMOS (CMOS) 3.3Vdc 4 Pad 2.5mm x 3.2mm Plastic Surface Mount (SMD)

ELECTRICAL SPECIFICATIONS

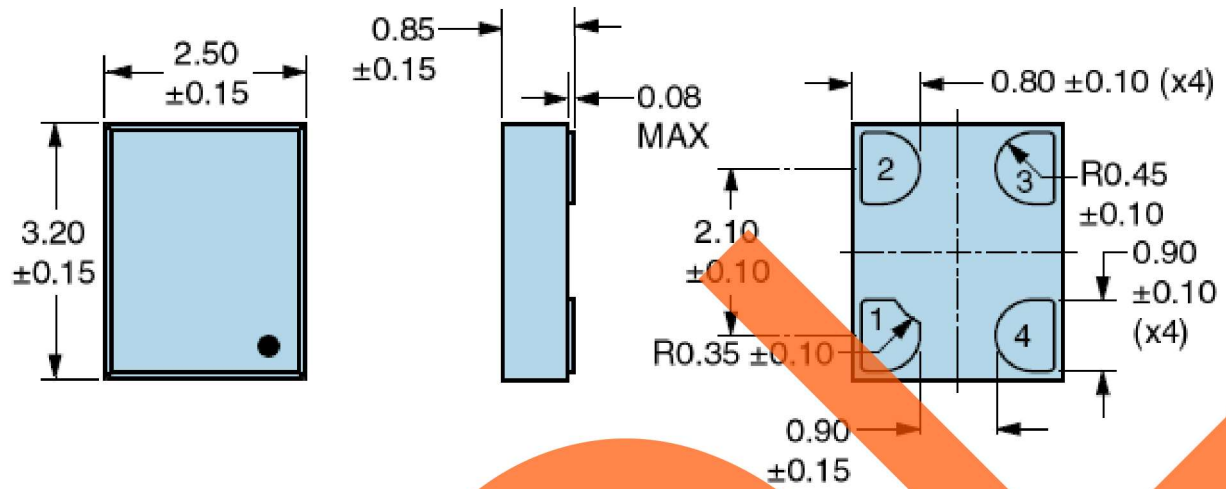
| | |
|---|--|
| Nominal Frequency | 1MHz to 125MHz |
| Frequency Tolerance/Stability | Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, and Output Load Change ±100ppm Maximum over 0°C to +70°C ±50ppm Maximum over 0°C to +70°C ±25ppm Maximum over 0°C to +70°C ±20ppm Maximum over 0°C to +70°C ±100ppm Maximum over -20°C to +70°C ±50ppm Maximum over -20°C to +70°C ±25ppm Maximum over -20°C to +70°C ±20ppm Maximum over -20°C to +70°C ±100ppm Maximum over -40°C to +85°C ±50ppm Maximum over -40°C to +85°C ±25ppm Maximum over -40°C to +85°C ±20ppm Maximum over -40°C to +85°C |
| Aging at 25°C | ±1.5ppm Maximum First Year |
| Supply Voltage | 3.3Vdc ±10% |
| Input Current | No Load 5mA Maximum over Nominal Frequency of 1MHz to 20MHz 6mA Maximum over Nominal Frequency of 20.000001MHz to 50MHz 7mA Maximum over Nominal Frequency of 50.000001MHz to 80MHz 9mA Maximum over Nominal Frequency of 80.000001MHz to 125MHz |
| Output Voltage Logic High (V_{OH}) | I _{OH} = -4mA 90% of V _{DD} Minimum |
| Output Voltage Logic Low (V_{OL}) | I _{OL} = +4mA 10% of V _{DD} Maximum |
| Rise/Fall Time | Measured from 20% to 80% of waveform 1.2nSec Typical, 3nSec Maximum |
| Duty Cycle | Measured at 50% of waveform 50 ±10(%) 50 ±5(%) |
| Load Drive Capability | 15pF Maximum |
| Output Logic Type | CMOS |
| Output Control Function | Tri-State (Disabled Output: High Impedance) Power Down (Disabled Output: Logic Low) |
| Output Control Input Voltage Logic High (V_{IH}) | 70% of V _{DD} Minimum or No Connect to Enable Output |
| Output Control Input Voltage Logic Low (V_{IL}) | 30% of V _{DD} Maximum to Disable Output |
| Power Down Output Enable Time | 5mSec Maximum (Disabled Output: Logic Low) |
| Tri-State Output Enable Time | 150nSec Maximum (Disabled Output: High Impedance) |
| Power Down Output Disable Time | 150nSec Maximum (Disabled Output: Logic Low) |
| Tri-State Output Disable Time | 150nSec Maximum (Disabled Output: High Impedance) |
| Standby Current | 10µA Maximum (Disabled Output: Logic Low) |
| Period Jitter (RMS) | 2pSec Typical, 4pSec Maximum |

| | |
|--|--------------------------------|
| RMS Phase Jitter (Fj = 900kHz to 7.5MHz; Random) | 0.5pSec Typical, 1pSec Maximum |
| RMS Phase Jitter (Fj = 12kHz to 20MHz; Random) | 1.5pSec Typical, 3pSec Maximum |
| Start Up Time | 5mSec Maximum |
| Storage Temperature Range | -65°C to +150°C |

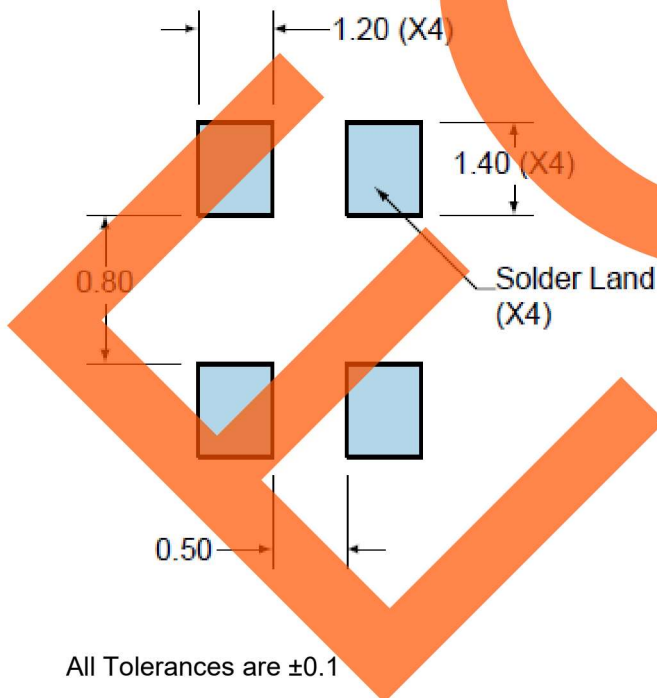
PART NUMBERING GUIDE



MECHANICAL DIMENSIONS



SUGGESTED SOLDER PAD LAYOUT

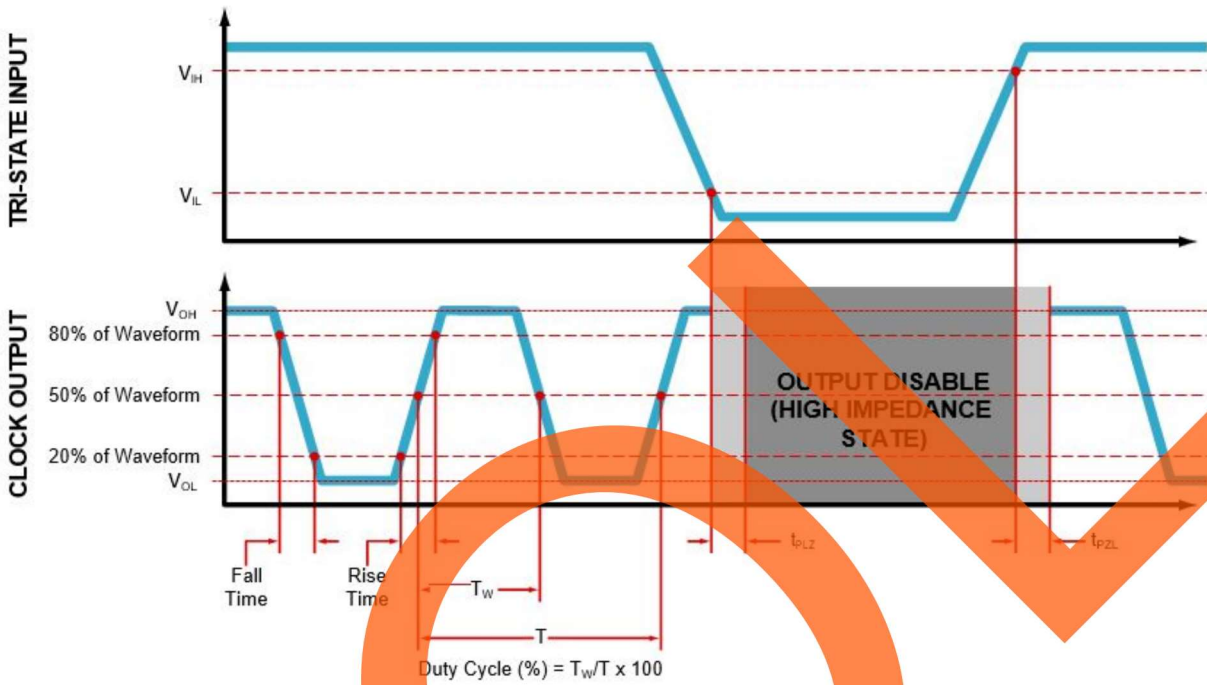


| PIN | CONNECTION |
|-----|-------------------------|
| 1 | Power Down Or Tri-State |
| 2 | Ground |
| 3 | Output |
| 4 | Supply Voltage |

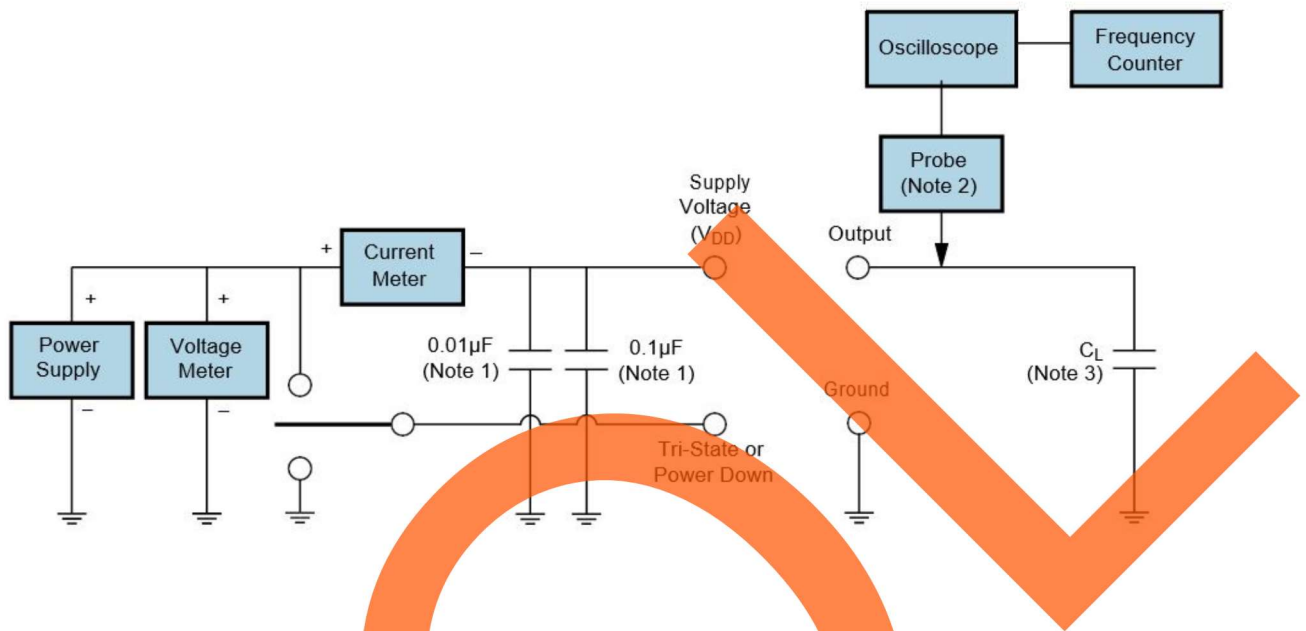
All Tolerances are ±0.1

All Dimensions in Millimeters

OUTPUT WAVEFORM & TIMING DIAGRAM



TEST CIRCUIT FOR CMOS OUTPUT



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low input capacitance (<12pF), 10X Attenuation Factor, High Impedance (>10Mohms), and High bandwidth (>300MHz) Passive probe is recommended.

Note 3: Capacitance value CL includes sum of all probe and fixture capacitance. See applicable specification sheet for 'Load Drive Capability'.

TAPE & REEL DIMENSIONS

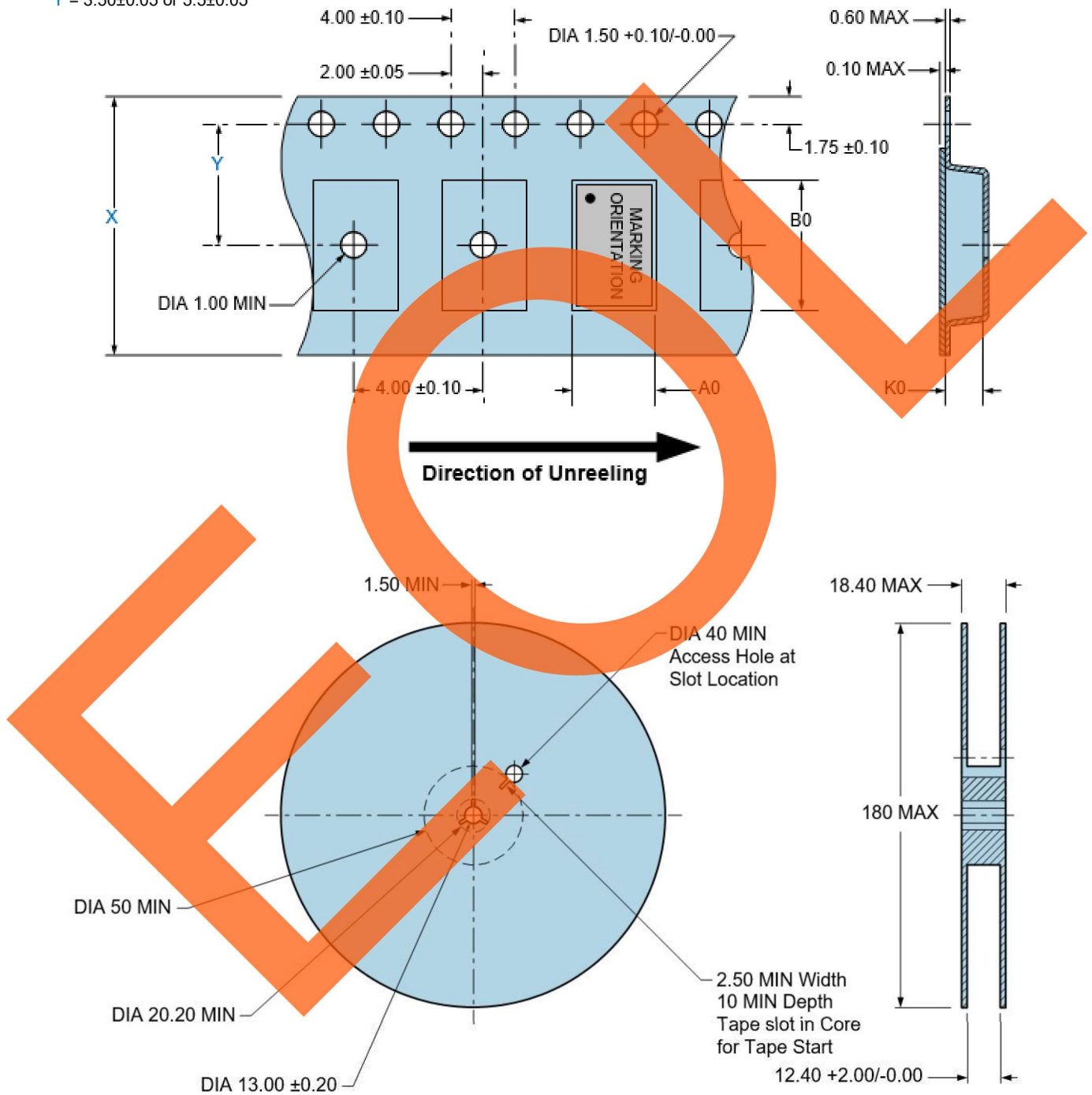
Quantity per Reel: 1,000 Units

All Dimensions in Millimeters

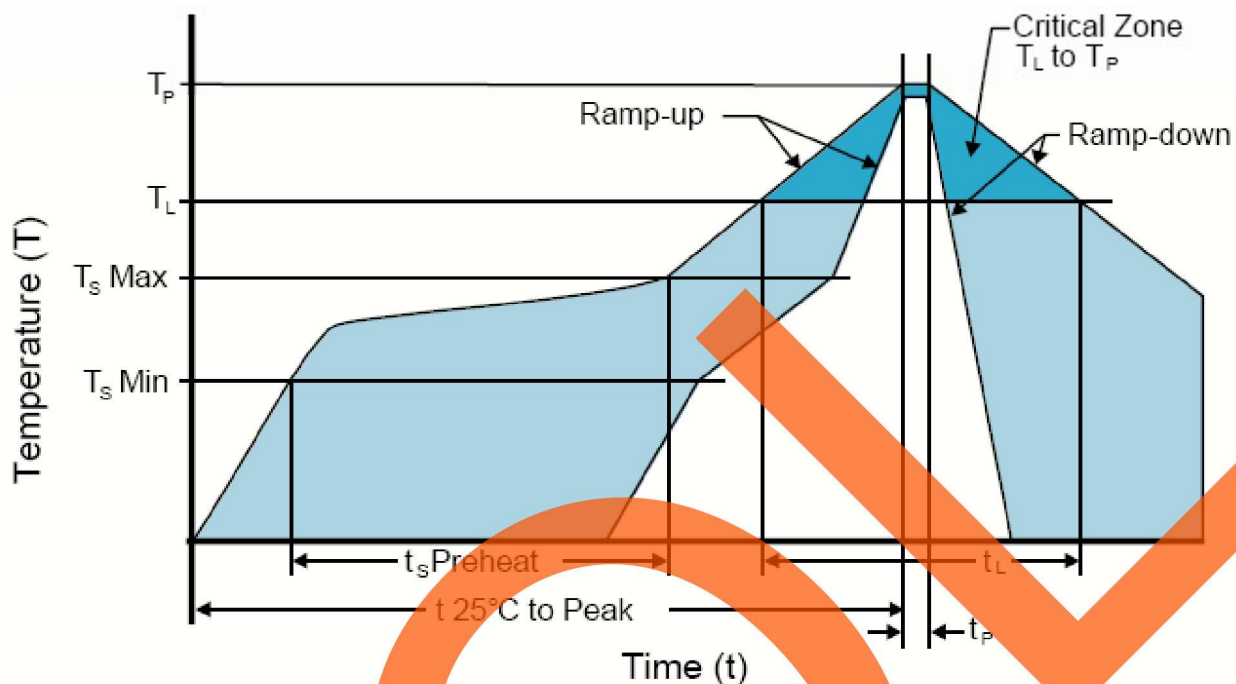
Compliant to EIA-481

X = 8.00±0.30 or 12±0.30

Y = 3.50±0.05 or 5.5±0.05



RECOMMENDED SOLDER REFLOW METHOD



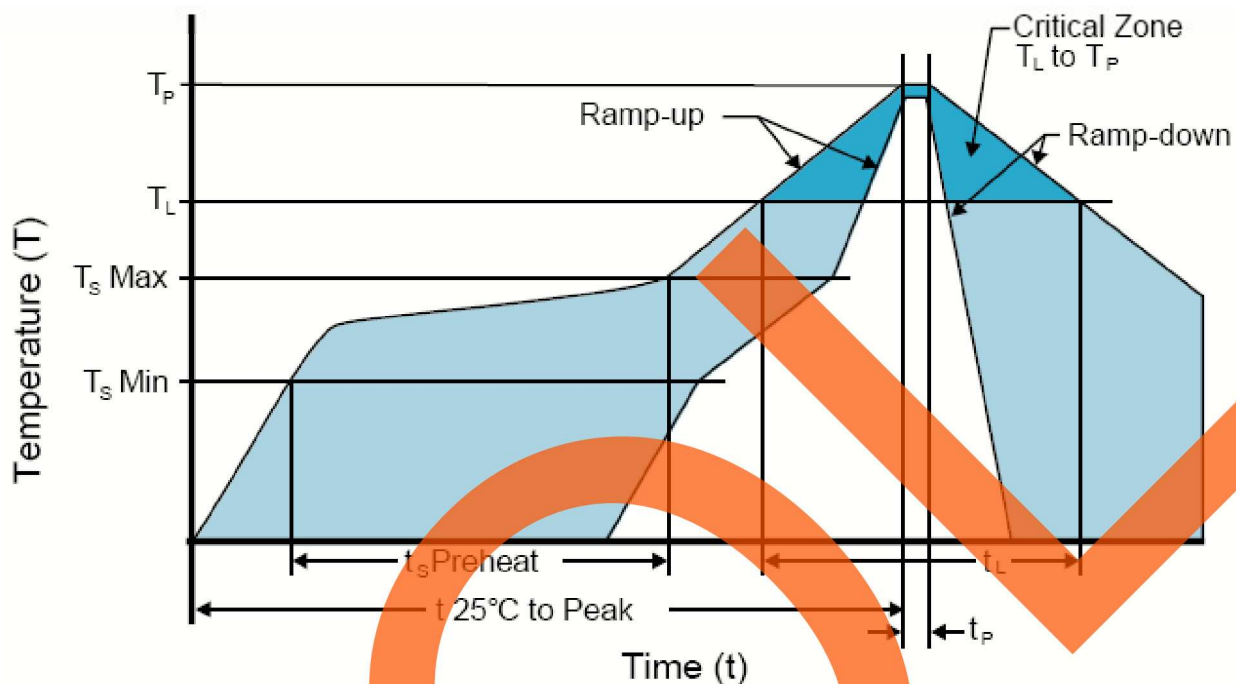
HIGH TEMPERATURE INFRARED/CONVECTION

| | |
|---|---|
| T _S MAX to T _L (Ramp-up Rate) | 3°C/Second Maximum |
| Preheat | |
| - Temperature Minimum (T _S MIN) | 150°C |
| - Temperature Typical (T _S TYP) | 175°C |
| - Temperature Maximum (T _S MAX) | 200°C |
| - Time (t _S MIN) | 60 - 180 Seconds |
| Ramp-up Rate (T_L to T_P) | 3°C/Second Maximum |
| Time Maintained Above: | |
| - Temperature (T _L) | 217°C |
| - Time (t _L) | 60 - 150 Seconds |
| Peak Temperature (T_P) | 260°C Maximum for 10 Seconds Maximum |
| Target Peak Temperature (T_P Target) | 250°C +0/-5°C |
| Time within 5°C of actual peak (t_p) | 20 - 40 Seconds |
| Ramp-down Rate | 6°C/Second Maximum |
| Time 25°C to Peak Temperature (t) | 8 Minutes Maximum |
| Moisture Sensitivity Level | Level 1 |
| Additional Notes | Temperatures shown are applied to body of device. |

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

RECOMMENDED SOLDER REFLOW METHOD



LOW TEMPERATURE INFRARED/CONVECTION

| | |
|---|--|
| T _S MAX to T _L (Ramp-up Rate) | 5°C/Second Maximum |
| Preheat | |
| - Temperature Minimum (T _S MIN) | N/A |
| - Temperature Typical (T _S TYP) | 150°C |
| - Temperature Maximum (T _S MAX) | N/A |
| - Time (t _S MIN) | 60 - 120 Seconds |
| Ramp-up Rate (T_L to T_P) | 5°C/Second Maximum |
| Time Maintained Above: | |
| - Temperature (T _L) | 150°C |
| - Time (t _L) | 200 Seconds Maximum |
| Peak Temperature (T_P) | 240°C Maximum |
| Target Peak Temperature (T_P Target) | 240°C Maximum 2 Times / 230°C Maximum 1 Time |
| Time within 5°C of actual peak (t_p) | 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time |
| Ramp-down Rate | 5°C/Second Maximum |
| Time 25°C to Peak Temperature (t) | N/A |
| Moisture Sensitivity Level | Level 1 |
| Additional Notes | Temperatures shown are applied to body of device. |

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)